



BGA/CSP DEVELOPMENT UPDATE SERVICE

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The first quarterly BGA/CSP update for 2002 features package and board developments in consumer products such as digital camcorders and cameras, including recent products from Sony. A special section provides insight into IC package assembly developments in Shanghai, China, with detailed coverage of the major contract assembly service providers, including their roadmaps for the future. Background information on IC manufacturing trends is also provided. The report covers packaging trends in Taiwan, including Advanced Chip Engineering Technology, a new contract assembly operation in Taiwan specializing in wafer level packaging. New packages are discussed, such as Intel's stacked and folded packages, Fujitsu's eight-chip stacked package, Sanyo's SiP, and Toshiba's stacked MCP. With the continued close movement in assembly and test, a special section has been devoted to an in-depth review of trends in strip testing.

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